

1N4933GP - 1N4937GP

Features

- Low forward voltage drop.
- High surge current capability.
- High reliability.
- High current capability.



DO-41
COLOR BAND DENOTES CATHODE

1.0 Ampere Glass Passivated Fast Recovery Rectifiers

Absolute Maximum Ratings* T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
I _{F(AV)}	Average Rectified Current .375" lead length @ T _A = 75°C	1.0	A
I _{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms single half-sine-wave Superimposed on rated load (JEDEC method)	30	A
P _D	Total Device Dissipation Derate above 25°C	2.73 18	W mW/°C
R _{θJA}	Thermal Resistance, Junction to Ambient	55	°C/W
T _{stg}	Storage Temperature Range	-65 to +175	°C
T _J	Operating Junction Temperature	-65 to +175	°C

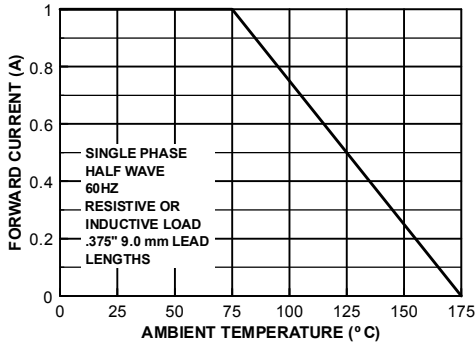
*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Electrical Characteristics T_A = 25°C unless otherwise noted

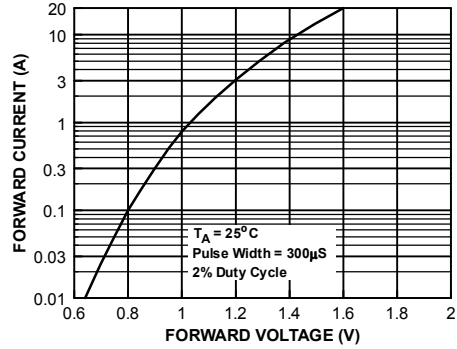
Symbol	Parameter	Device					Units
		4933G	4934	4935	4936	4937	
V _{RRM}	Maximum Repetitive Reverse Voltage	50	100	200	400	600	V
V _{RMS}	Maximum RMS Voltage	35	70	140	280	420	V
V _R	DC Reverse Voltage (Rated V _R)	50	100	200	400	600	V
I _R	Maximum Instantaneous Reverse Current @ rated V _R T _A = 25°C T _A = 125°C	5.0 100					μA μA
t _{rr}	Maximum Instantaneous Reverse Recovery Time I _F = 0.5 A, I _R = 1.0 A, I _{RR} = 0.25A	150					ns
V _{FM}	Maximum Forward Voltage @ 1.0 A	1.2					V
C	Typical Junction Capacitance V _R = 4.0 V, f = 1.0 MHz	15					pF

Typical Characteristics

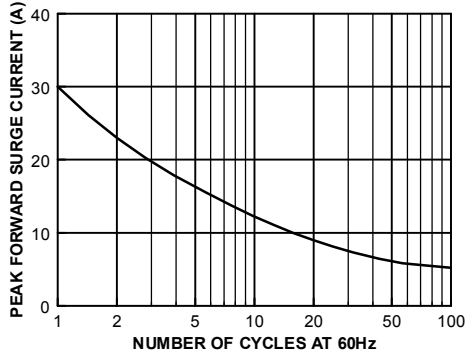
Forward Current Derating Curve



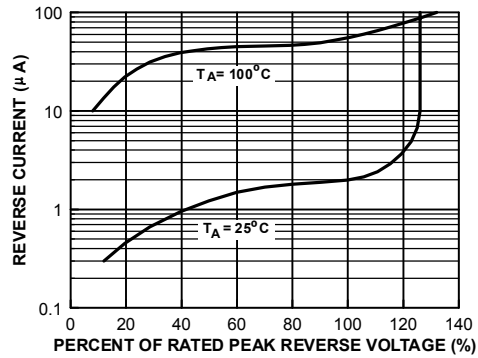
Forward Characteristics



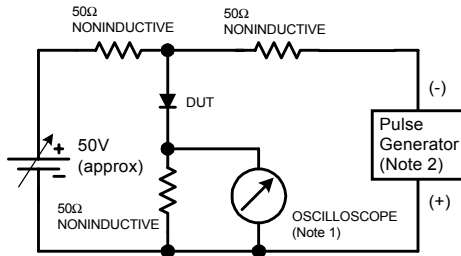
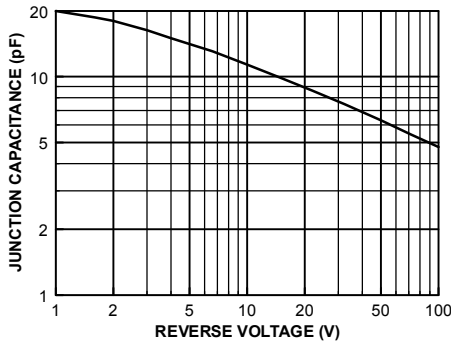
Non-Repetitive Surge Current



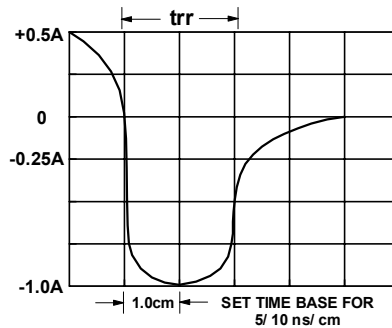
Reverse Characteristics



Typical Junction Capacitance



- NOTES:
 1. Rise time = 7.0 ns max; Input impedance = 1.0 megaohm 22 pf.
 2. Rise time = 10 ns max; Source impedance = 50 ohms.

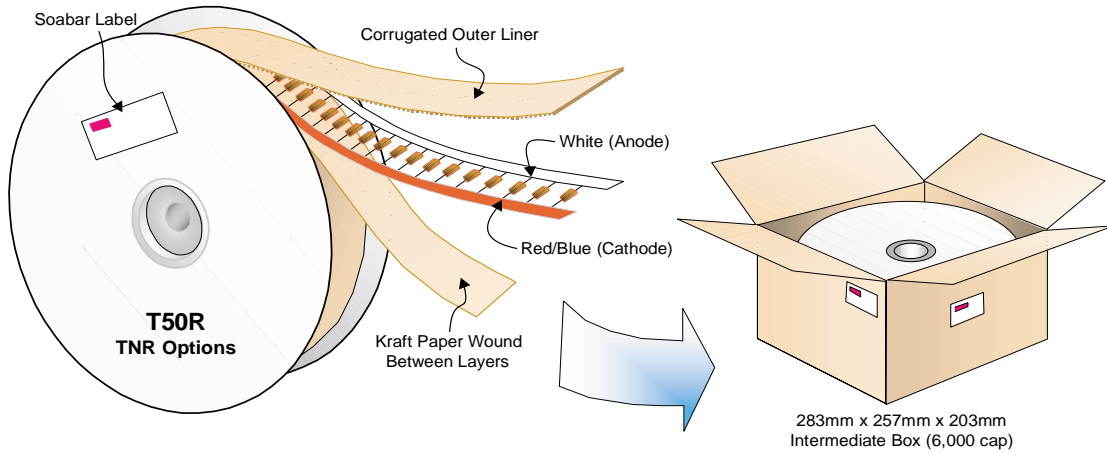


Reverse Recovery Time Characteristic and Test Circuit Diagram

DO-41 (Glass) Tape and Ammo Data



DO-41 (Glass) Packaging Configuration: Figure 1.0



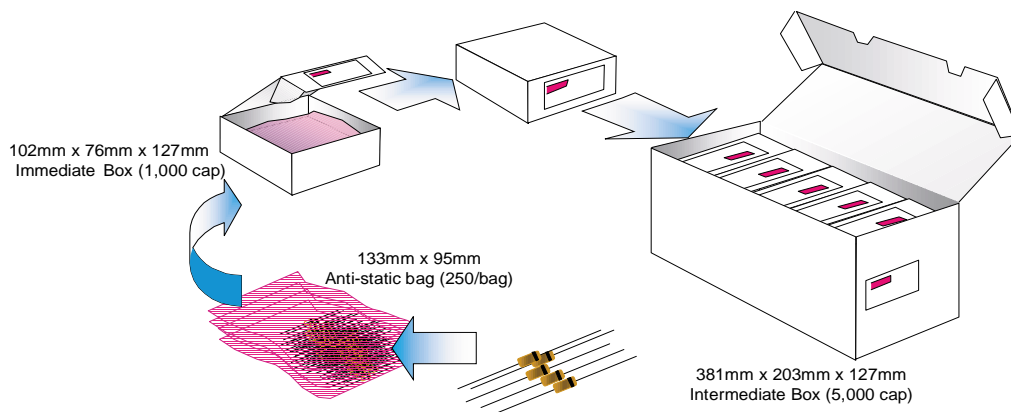
DO-41 (Glass) Packaging Information Table : Figure 2.0

DO-41 (Glass) Packaging Information			
Packaging Option	T50R	T50A	Standard (no flow code)
Packaging type	TNR	Ammo	Bag
Qty per Reel/Tube/Bag	3,000	3,000	250
Reel Size (inch diameter)	10.5	-	-
Inside Tape Spacing (mm)	52	52	-
Int Box Dimension (mm)	283x257x203	406x267x184	381x203x127
Max qty per Box	6,000	30,000	5,000
Weight per unit (gm)	0.320	0.320	0.320
Weight per Reel (kg)	1.356	1.077	-
Note/Comments			Bulk

Soabar Label sample

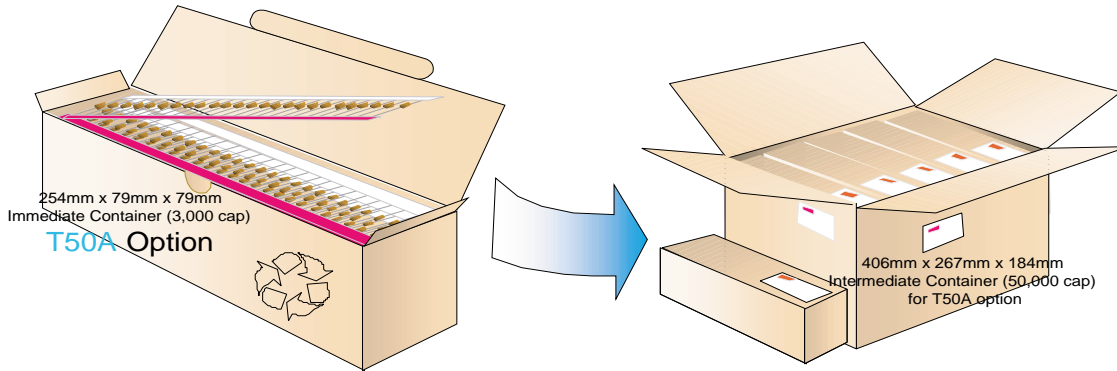
FAIRCHILD SEMICONDUCTOR™	P.O. No.	BLK-BRN
TYPE 1N4744A	MARK	
REV A2	PART No.	
PKG	EC No.	
QTY 3,000	M.O. No.	OX5046F035
Q.C.	DATE	D9903
MFD. UNDER US PAT 3,025,589 & OTHER US PATS & APPLICATIONS		

DO-41 (Glass) Bulk Packing Configuration: Figure 3.0

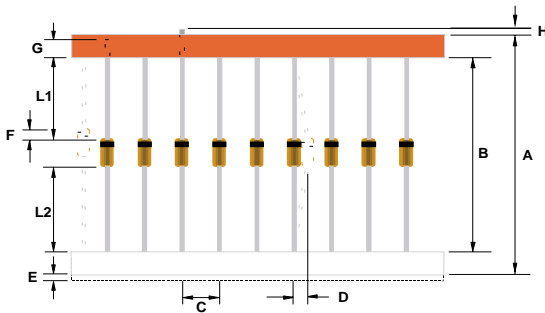


DO-41 (Glass) Tape and Ammo Data, continued

DO-41 (Glass) Ammo Packing Configuration: Figure 4.0



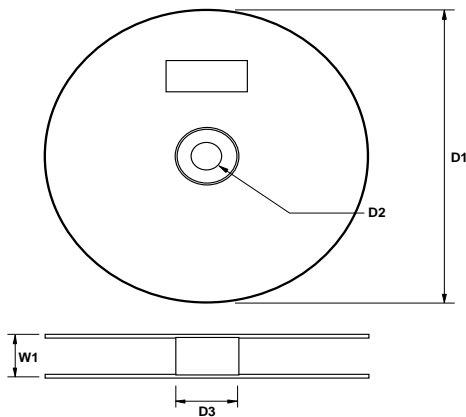
DO-41 (Glass) Taping Dimension: Figure 5.0



TAPING DIMENSIONS

	INCH	MM	MILS	NOTES
A	2.520 +0.066/ -0.027	64.00 +1.69/ -0.69	2519 +66.5/ -27.0	Overall width
B	2.047±0.027	52 ±0.69	2047±27	Inside Tape Spacing
C	0.200 ±0.0157	5.08 ±0.40	200 ±15.7	Component Pitch
D	0.047(max)	1.2(max)	47(max)	Component Misalignment
E	0.022(max)	0.55(max)	22(max)	Tape Mismatch
F	0.027(max)	±0.69	±27	Units in line w/ one another
G	0.126(min)	3.2(min)	126(min)	Lead amount between tapes
H	0	0	0	Lead amount beyond tapes
L1-L2	±0.027	±0.69	±27	Delta between two leads

DO-41 (Glass) Reel Dimension: Figure 6.0



REEL DIMENSIONS

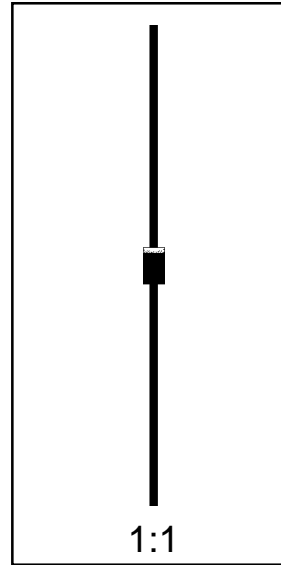
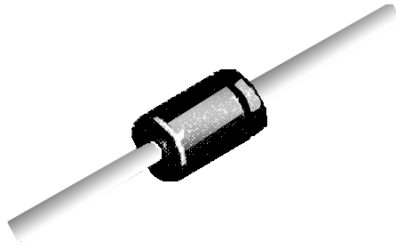
ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	10.375	10.625
Arbor Hole Diameter (Standard)	D2	1.245	1.255
Core Diameter	D3	3.190	3.310
Flange to Flange Outer Width	W1		3.400

Note: All Dimensions are in inches

DO-41 (Glass) Package Dimensions



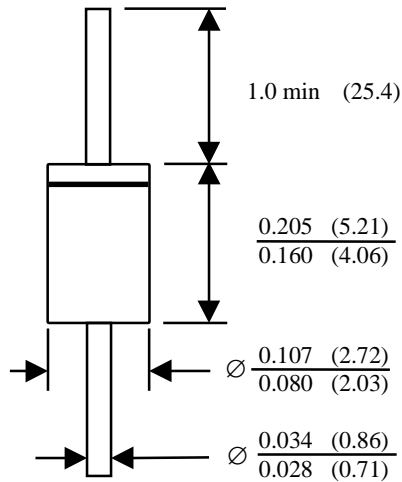
DO-41 (FS PKG Code D4)



Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.32



TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACE ^x TM	FAST ^r TM	PowerTrench [®]	SyncFET TM
Bottomless TM	GlobalOptoisolator TM	QFET TM	TinyLogic TM
CoolFET TM	GTO TM	QS TM	UHC TM
CROSSVOLT TM	HiSeC TM	QT Optoelectronics TM	VCX TM
DOME TM	ISOPLANAR TM	Quiet Series TM	
E ² CMOS TM	MICROWIRE TM	SILENT SWITCHER [®]	
EnSigna TM	OPTOLOGIC TM	SMART START TM	
FACT TM	OPTOPLANAR TM	SuperSOT TM -3	
FACT Quiet Series TM	PACMAN TM	SuperSOT TM -6	
FAST [®]	POP TM	SuperSOT TM -8	

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.